客户（Customer）:_____

承认书
Approval Sheet

谨致执事者：兹提供敝公司之有关详细规格及图面数据,敬请给予办理试认定手续.
同时敬请送返一份附有贵公司签认之测试认定后之样品承认书.

We are pleased in sending you herewith on specification and drawings for your approval.
Please return to us one copy “Approval sheet” with your approved signature.

型号 (Model No.)：A-SI2020R6AGHB1C-C01-2T

发文日期（Issue Date）: 2023/10/16 承认日期（Approved Date）:_____

Checking signature of Amicc

Designer	Checker	Approver
Katryn		

Approval signature of customer

Designer	Checker	Approver

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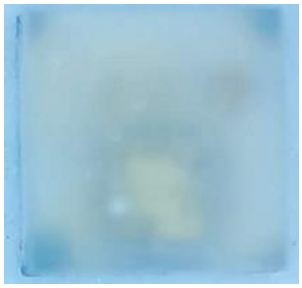
LED Built-in IC Type ▪ Top view Full-color 2020 Package

A-SI2020R6AGHB1C-C01-2T



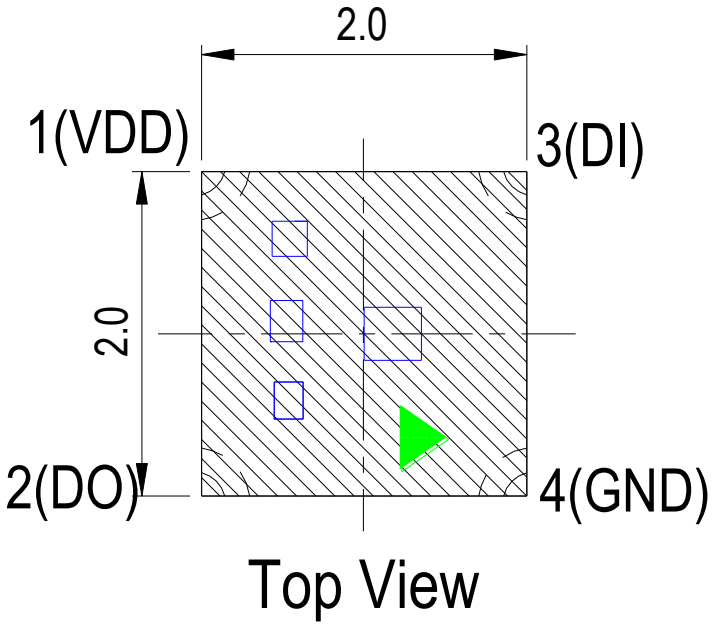
Features

- Top SMD integrated with high quality external control single line serial cascade constant current IC.
- Support for singe wire communication, serial connection.
- Constant current output current 5mA.
- Grayscale adjustable circuit 256 grayscale adjustable.
- Display data double latch, transfer data does not affect display.
- Single line data transmission, unlimited cascade.
- Built-in high-precision oscillator.
- Display maximum refresh rate up to 4.5Khz.
- Pb-free
- RoHS compliant

Applications

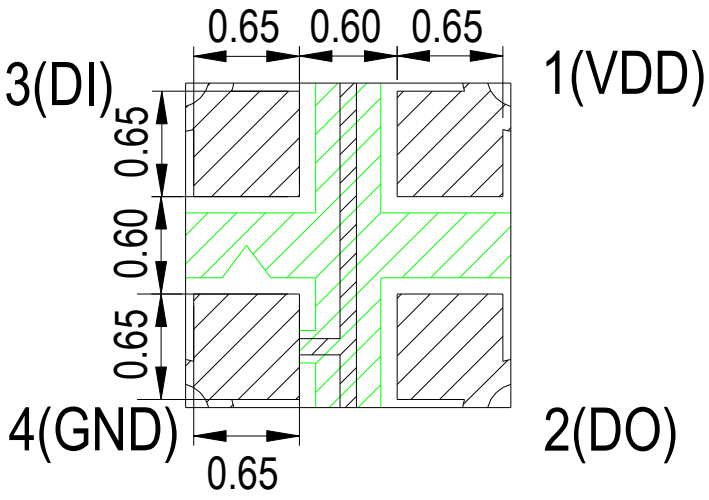
- Full color LED string light, LED full color module
- LED super hard and soft lights, LED appearance / scene lighting
- LED point light source, LED pixel screen
- LED shaped screen, Electrical equipment Marquee

Package Dimensions



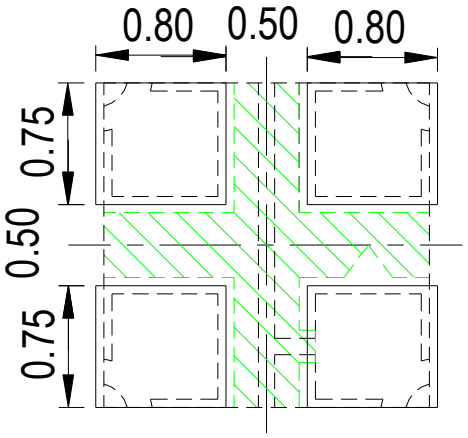
Top View

Side View



Bottom View

Recommended Solder Pad



Note:
Tolerance unless mentioned is ±0.1mm,Unit = mm

Pin diagram and functions:

NO.	Symbol	Pin name	Function description
1	VDD	Power Supply	5V
3	DI	Data input	Built-in Pull down resistance
4	GND	Ground	Signal ground
2	DO	Data output	Built-in Pull down resistance@input mode

Electrical Characteristics（Limit parameter,Ta=25℃，VDD=12V,VSS=0V）

Parameter	Symbol	Range	Company
Voltage	V_{DD}	-0.4~+5.4	V
Logic input voltage	V_I	-0.4～VDD+0.4	V
Working temperature	Topt	-40~+85	℃
Storage temperature	Tstg	-40~+100	℃
ESD(Human Body Model)	V_{ESD}	2000	V

RGB LED Photoelectric parameters

Color	I_F=5mA	
	Dominate Wavelengt(nm)	Iv (mcd)
R	615~630	57~140
G	515~535	180~450
B	460~475	36~90

Typical Electro-Optical Characteristics Curve(Chip code: R6A)

Fig.1-Relative Luminous Intensity vs.Junction Temperature

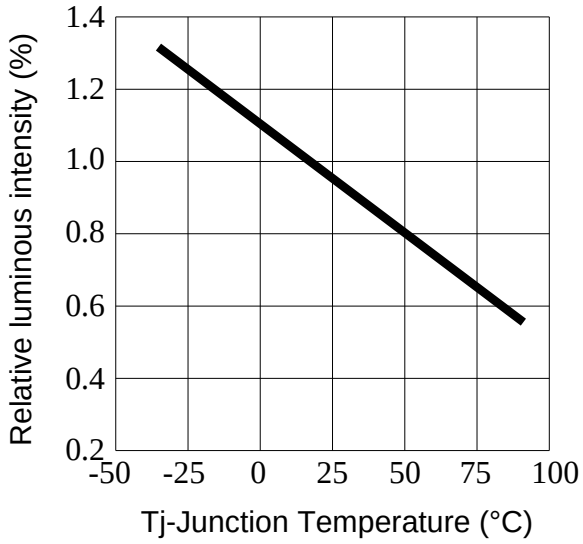


Fig.2-Relative Luminous Intensity vs. Forword Current

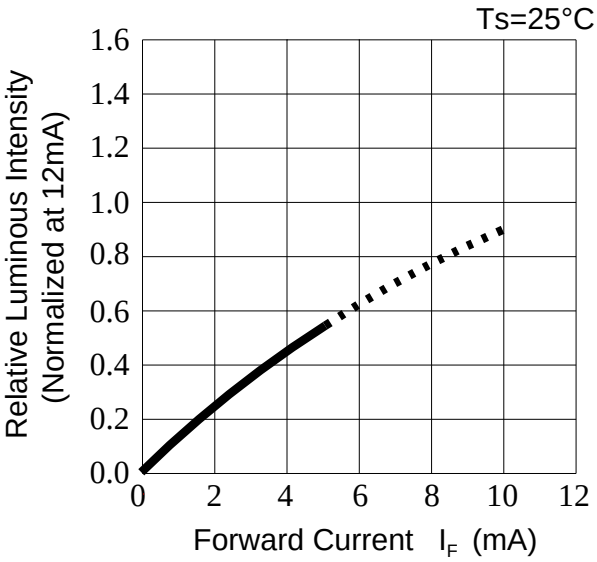


Fig.3-Max.Driving Forward Current vs.Soldering Temperture

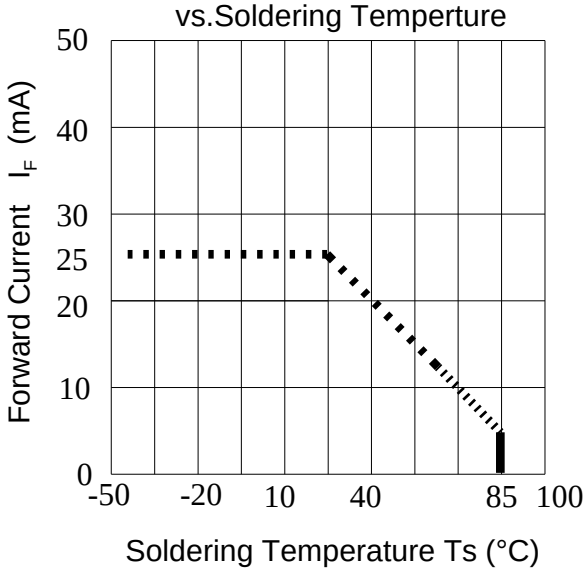
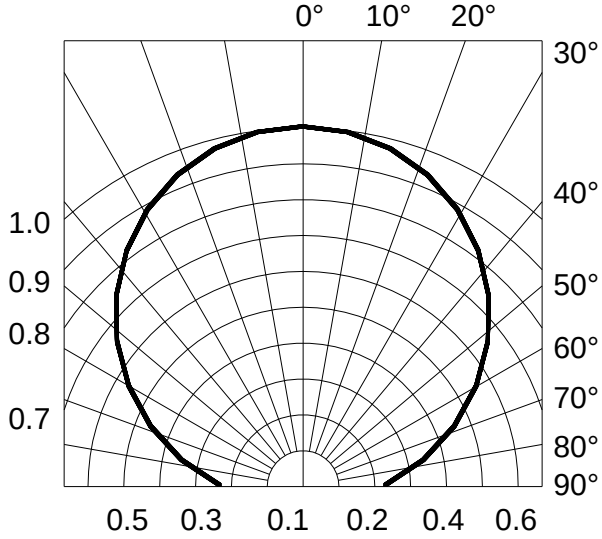


Fig.4-Radiation Diagram Ta=25°C



Typical Electro-Optical Characteristics Curve(Chip code: GH/B1)

Fig.1-Relative Luminous Intensity vs.Junction Temperature

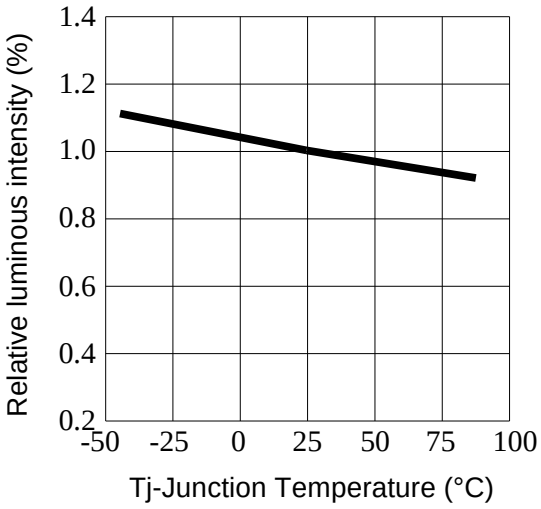


Fig.2-Relative Luminous Intensity vs. Forword Current

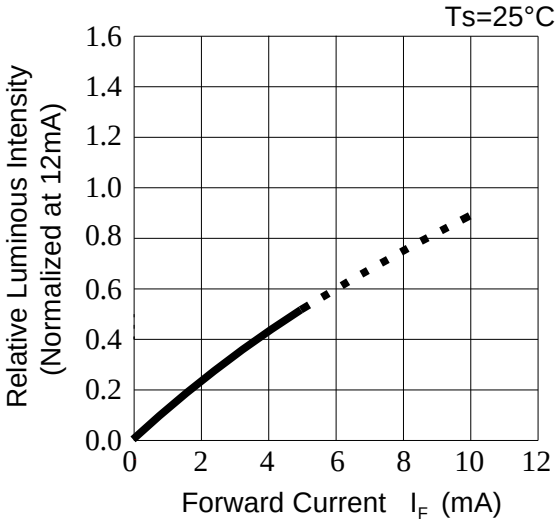


Fig.3-Max.Driving Forward Current vs.Soldering Temperture

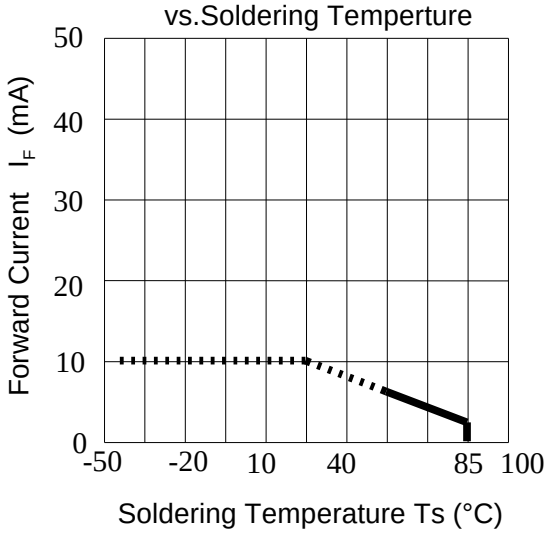
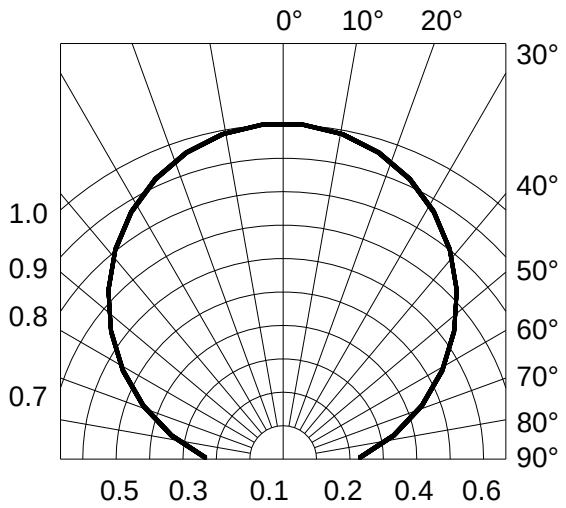


Fig.4-Radiation Diagram Ta=25°C

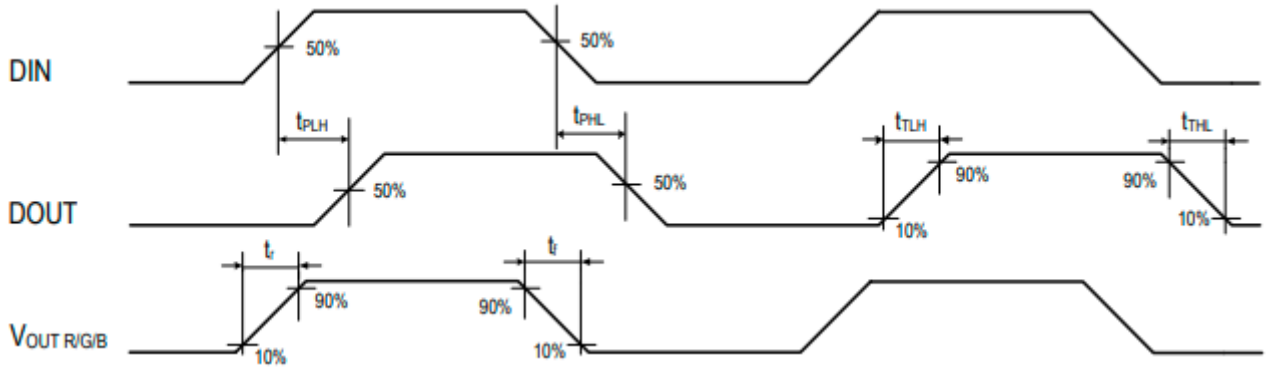


Electrical Characteristics (Without special instructions ,Ta= -40～+80℃,VDD=9~12V,VSS=0V)

Parameter	Symbol	Min.	Avg.	Max.	Company	Test conditions
Chip internal supply voltage	V_{DD}	3.0	---	5.5	V	---
High level input voltage	V_{IH}	0.7*VDD	---	---	V	Din
Low level input voltage	V_{IL}	---	---	0.3*VDD	V	Din
RGB Maximum Sink current	I_{sink}	----	5	----	mA	VDD=5V

Dynamic Parameter (Ta=25℃)：

Parameter	Symbol	Min.	Avg.	Max.	Company	Test conditions
Data transmission speed	F_{DIN}	---	4.5	---	KHz	
DOUT Transmission delay	T_{PLH}	---	80	---	ns	DIN→DOUT
	T_{PHL}	---	80	---	ns	
I out rise time	T_r	---	500	---	ns	VOUT=1V R、G、B=5mA
	T_f	---	500	---	ns	

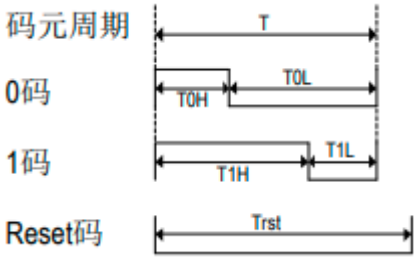


Data Transfer Time （TH+TL=1.25μs±600ns）

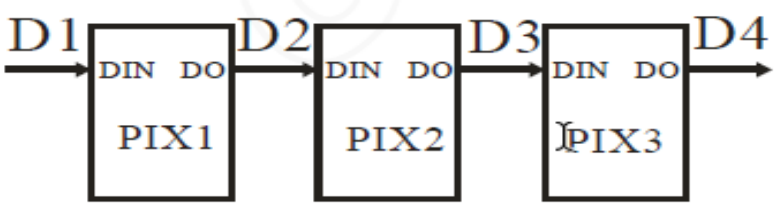
T0H	0 code, High time	0.3μs	±0.15μs
T1H	1 code, High time	0.9μs	±0.15μs
T0L	0 code, Low level time	0.9μs	±0.15μs
T1L	1 code, Low level time	0.3μs	±0.15μs
Trst	Reset,Code Low level time	>200μs	

Timing Waveform（Ta=25℃）：

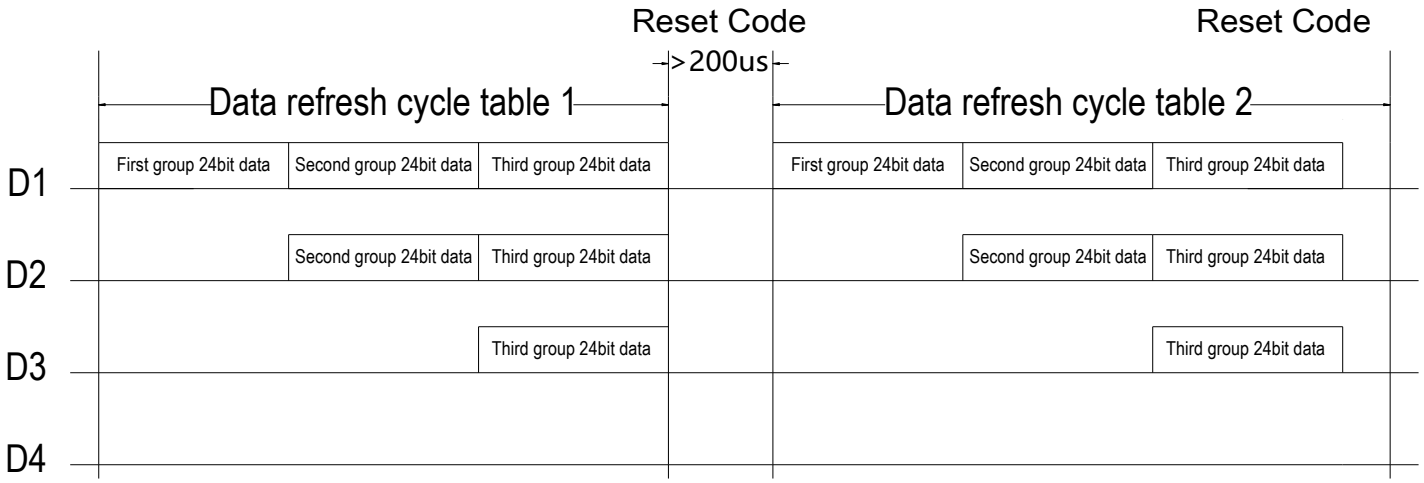
Input code type:



Connection mode:



Data Transmission Mode（Ta=25℃）:



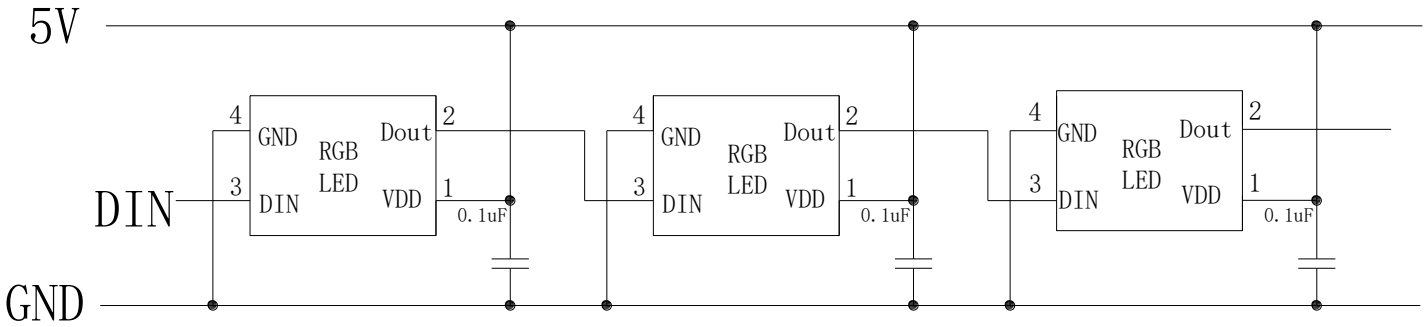
Note:
Where D1 is the data sent to the MCU side, D2, D3, D4 are automatically shaping and forwarding data for cascaded circuits

24bit Data Structure（Ta=25℃）:

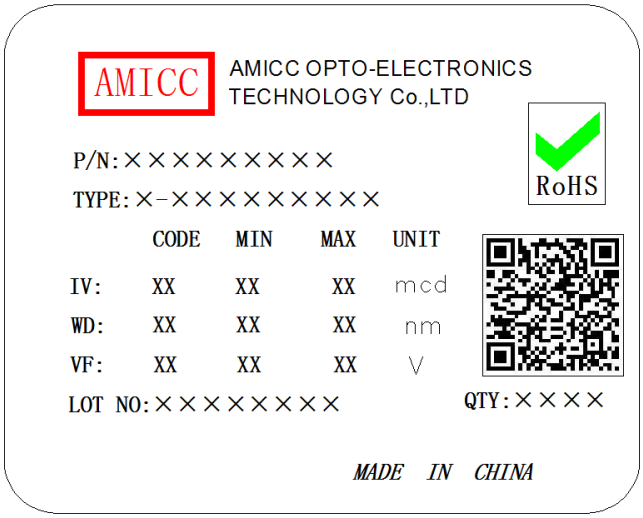
R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4
G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0

Note:
High priority, in accordance with the order of RGB to send data (R7 ~ R6 ~ B0)

Typical Application Circuit:

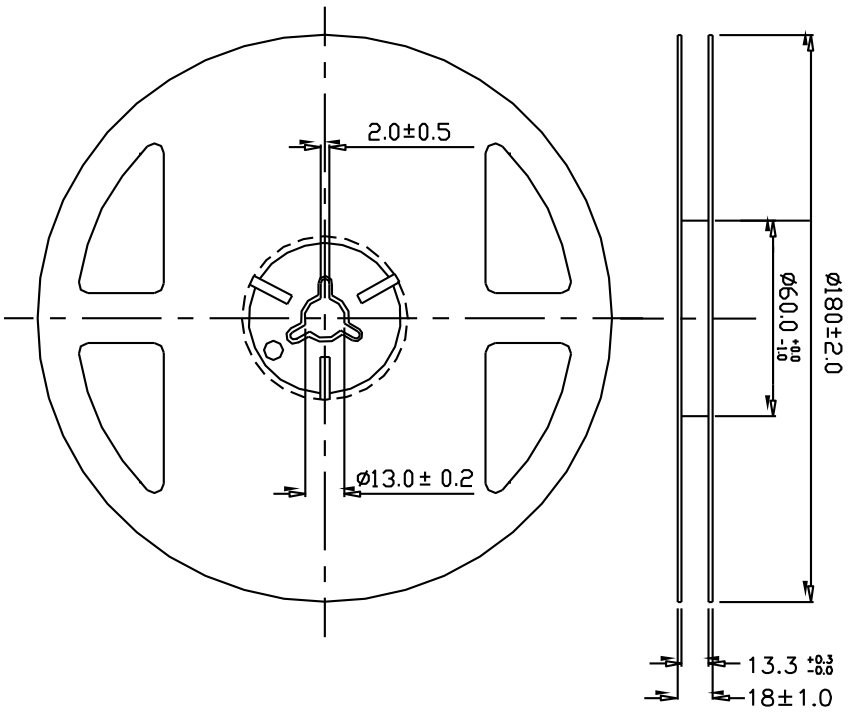


Label Explanation



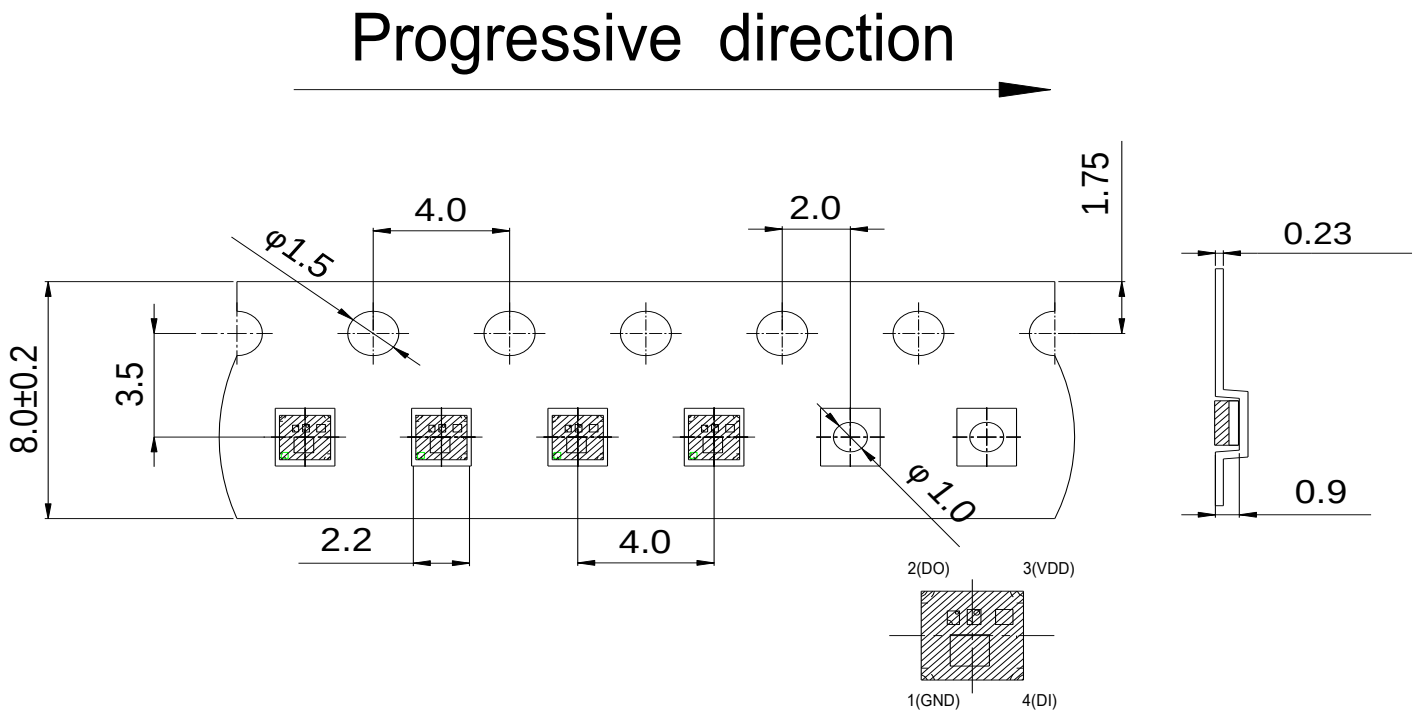
- CPN: Customer's Product Number
- P/N: Product Number
- TYPE :Part NO.
- LOT NO.: Lot Number
- QTY: Packing Quantity

Reel Dimensions



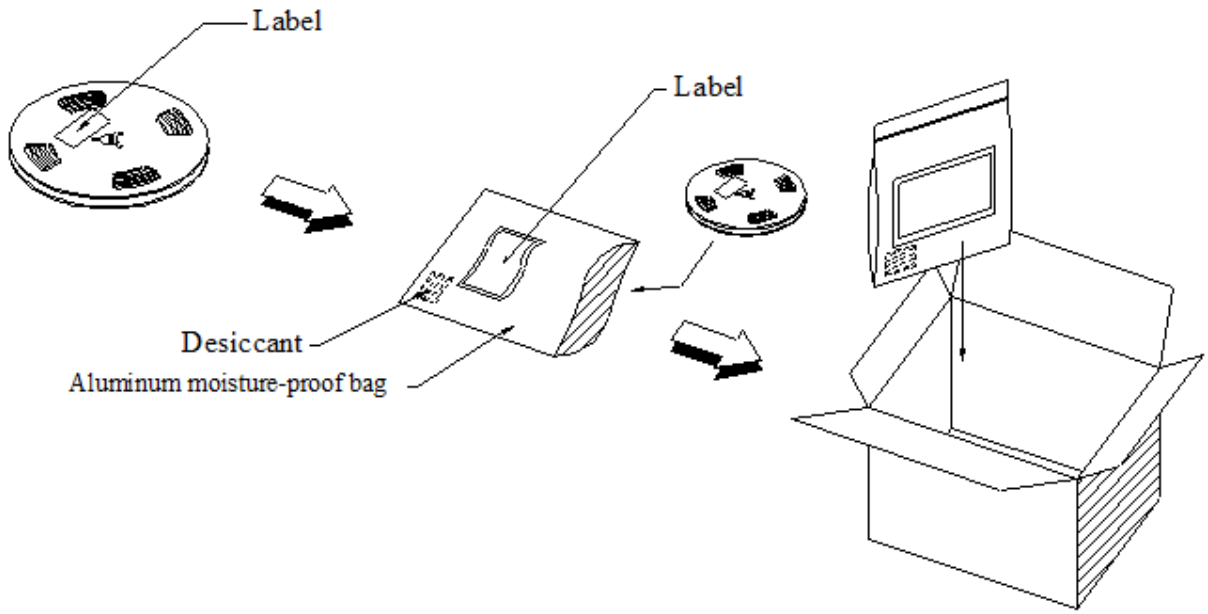
Note:
Tolerances unless mentioned ±0.1mm,Unit = mm

Carrier Tape Dimensions: Loaded Quantity 2000pcs Per Reel



Notes:
1.Tolerance unless mentioned is ±0.1mm, Unit = mm.
2.Minimum packing amount is1000pcs per reel.

Moisture Resistant Packing Process



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity	Ta=85℃,85%RH	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Ta=-40℃	1000 Hrs.	22 PCS.	0/1
6	High Temperature Storage	Ta=100℃	1000 Hrs.	22 PCS.	0/1
7	DC Operation Life	Ta=25℃ VDD=5V	1000 Hrs.	22 PCS.	0/1

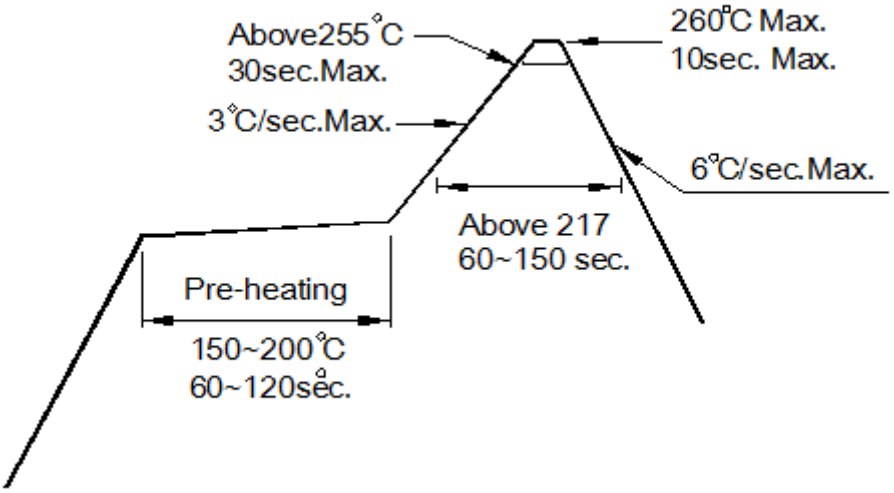
Precautions for Use

1. Dust and cleanliness
1.1.To keep the working environment clean. Avoid dust falling onto LED surface. Open the bag on the priority, installed LED components should be stored in a clean container, etc.
1.2. Do not use ultrasound to clean LEDs, if the product must use ultrasound, then evaluate some of the parameters affecting the LED

2.Damp-proof packing
LED was packed in aluminum film bags to prevent LED from absorbing moisture during transportation and storage, and desiccant was placed in the bags to absorb moisture.

3. Memory
3.1.In order to avoid LED moisture absorption, LED in bulk or pasted should be stored in a drying box or container with desiccant. Alternatively, it may be stored for a short period of time in the following environments:
temperature: 5℃~30℃ Humidity: less than 60%
3.2. When using LED, the aluminum film electrostatic bag should be welded quickly after opening, and the remaining LED should be sealed again. After opening the aluminum film bag, the LED should be refluxed within 1 week.
If you need to bake, please refer to the following baking temperature:
Bake in oven at 70 ℃ ±5 ℃ for not less than 24 hours

4. Soldering Condition
4.1 Pb-free solder temperature profile



4.2 Reflow soldering should not be done more than two times.
4.3 When soldering, do not put stress on the LEDs during heating.
4.4 After soldering, do not warp the circuit board.

5. Anti-static and surge
5.1. Static electricity and surge can hurt LED.
5.2. In order to protect LED, no matter what time and occasion, as long as access to the LED, have to wear antistatic wrist strap, anti-static foot straps and anti-static gloves.
5.3. All installations and instrumentation shall be grounded.
5.4. In circuit design, the possibility of eliminating the harm of surge to LED should be considered.